POEB2FB

Power over ethernet (PoE)/PD flyback transformer



Product features

- · Flyback topology
- · IEEE 802.3xx
- Up to 250 kHz switching frequency
- EFD20 SMT package (29.3 mm x 21.8 mm x 12 mm)
- · Input range from 10 V to 60 V
- 1500 Vac isolation between primary and secondary
- · Five power levels: 24, 30, 40, 42 and 60 watts
- · Low leakage inductance
- · Ferrite core material
- · Moisture sensitivity level (MSL): 1

Applications

- Lighting
- · Industrial automation
- · Security systems
- · VoIP phone systems
- · Network and Bluetooth access points
- · Network routers, repeaters
- · Uninterruptible power supplies (UPS)
- · Retail point-of-information (POI) systems
- · Vending and gaming machines
- · Remote cameras

Environmental compliance and general specifications

- Storage temperature (component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)









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Product specifications

Turns ratio
Schematic 1: Pri : Sec 1 :
Sec 2) : Aux
Schematic 2: Pri : Sec 1 :
Sec 2 : Aux)
Schematic 3: Pri) : Sec
1 : Aux)
Schematic 4: Pri : Sec

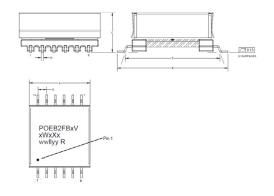
| Part number⁴ | Output power (W) | OCL¹ (µH) ±10% | SCL² (µH) maximum | 3 sat (A) | 1 : Aux Schematic 5: Pri : Sec 1 : Aux ±3% | Output | DCR (mΩ) maximum @ +25 °C (Pri) | DCR (mΩ) maximum @ +25 °C (Sec 1) | DCR (mΩ) maximum @ +25 °C (Sec 2) | DCR (mΩ) maximum @ +25 °C (Aux) | Schematic |
|------------------|------------------------|----------------------|-------------------------|---------------------|---|----------------------|--|--|--|--|-----------|
| POEB2FB1V24W2X12 | 24 | 11.5 | 0.5 | 3 | 1: 1 :0.9: 0.9 | (2) x 12.0 V | 28 | 23 | 130 | 130 | 1 |
| POEB2FB1V30W2X5 | 30 | 100 | 1 | 1 | 1:0.182:0.227:0.409 | (2) x 5.0 V | 100 | 7 | 70 | 260 | 2 |
| POEB2FB1V40W1X5 | 40 | 100 | 2 | 1 | 1:0.25:0.625 | (1) x 5.0 V @ 8.0 A | 150 | 11 | - | 215 | 3 |
| POEB2FB1V42W1X12 | 42 | 100 ± 12% | 1 | 1 | 1:0.5:0.5 | (1) x 12.0 V @ 3.5 A | 100 | 18 | - | 260 | 4 |
| POEB2FB1V60W1X12 | 60 | 70 | 1 | 1.6 | 1:0.35:0.3 | (1) x 12.0 V @ 5.0 A | 85 | 7.2 | - | 120 | 5 |

- 1. Open circuit inductance (OCL) is for the primary, test parameters: 100 kHz, 0.1 $V_{\rm rms}$, 0.0 Adc, +25 °C
- 2. Short circuit inductance (SCL) is for the primary with the other windings shorted, test parameters: 100 kHz, 0.1 V_{mot} 0.0 Adc, +25 °C
- 3. $\rm I_{sat}$ is for the primary, peak current for less than or equal to 10% rolloff @ +25 $^{\circ}C$
- 4. Part Number Definition: POEB2FBxVxWxXx

POEB2FB=Product code and size

xVxW, xV=Version indicator, xW= Output power, xXx=number of outputs and output voltage

Mechanical parameters, schematic, pad layout (mm)



| Dimension | Value | | |
|-----------|---------------|--|--|
| A | 21.85 maximum | | |
| В | 29.3 maximum | | |
| С | 12.0 maximum | | |
| D | 24.6 typical | | |
| E | 3.0 ± 0.3 | | |
| G | 0.65 ± 0.15 | | |

Part marking: Dot indicates pin 1, POEB2FB = Product code and size, xV=Version indicator, xW= Output power, xXx=number of outputs and output voltage.

wwllyy R= Lot code

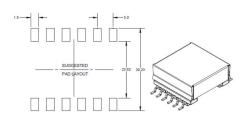
All pin length doesn't include tin icicles

All soldering surfaces to be coplanar within 0.13 millimeters Tolerances are ± 0.25 millimeters unless stated otherwise

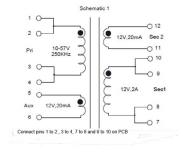
Pad layout tolerances are ±0.1 millimeters unless stated otherwise

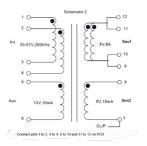
Traces or vias underneath the transformer is not recommended

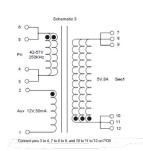
Recommended PCB Layout

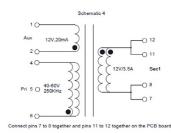


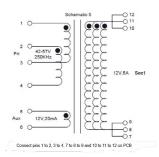
Schematic





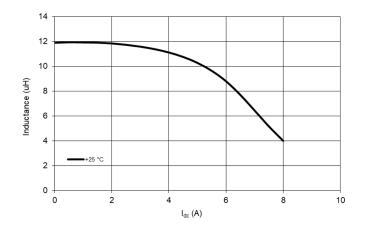




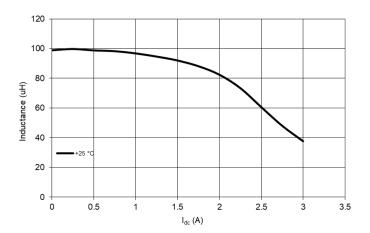


OCL (inductance) vs current characteristics

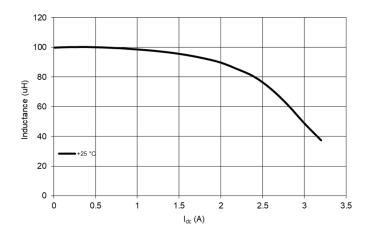
POEB2FB1V24W2X12



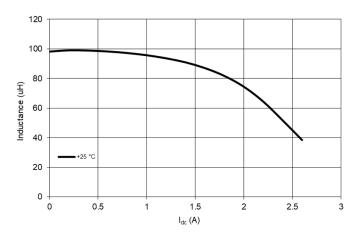
POEB2FB1V30W2X5



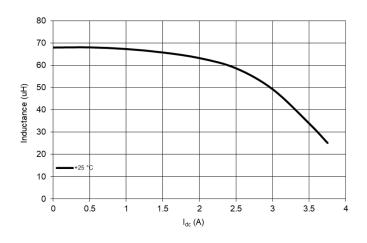
POEB2FB1V40W1X5



POEB2FB1V42W1X12

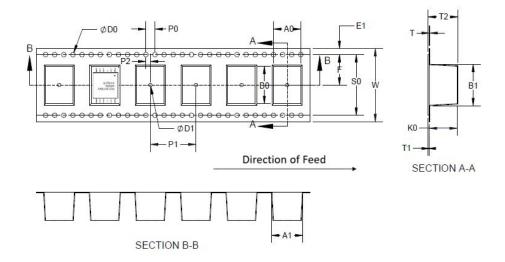


POEB2FB1V60W1X12



Packaging information (mm)

Supplied in tape and reel packaging, 13" diameter reel (EIA-481 compliant) 150 parts per reel



| Dimension | Value |
|--------------|-------|
| W ± 0.30 | 44 |
| F ± 0.10 | 20.2 |
| E1 ± 0.10 | 1.75 |
| P0 ± 0.10 | 4 |
| P1 ± 0.10 | 28 |
| P2 ± 0.15 | 2 |
| D0 + 0.10/-0 | 1.5 |
| D1 minimum | 2 |
| A0 ± 0.10 | 22 |
| A1 ref. | 20.3 |
| B0 ± 0.10 | 30 |
| B1 ± 0.1 | 23 |
| K0 ± 0.10 | 13 |
| T ± 0.05 | 0.5 |
| T1 maximum | 0.1 |
| T2 maximum | 13.7 |
| S0 | 40.4 |

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General specifications

Reflow: MIL-STD-202G Condition J, +245 °C ± 5 °C, 30 s ± 5 s, 1 times reflow

Solderability: J-STD-002. 8 hours steam age test, Flux type: ROL0, Solder: ± 245 °C ± 5 °C

Mechanical shock: MIL-STD-202 Method 213. Half-sine shock pulse, peak=100 g's, 6.0 ms, total 18 shocks

Vibration: MIL-STD-202, Method 204. Gravity= 10 g, Frequency= 10 Hz to 55 Hz to 10 Hz, Direction: 3 (X,Y, Z), each 12 cycles, Duration= 20 minutes in each direction

Salt spray: GB/T6461-2002, Salt spray concentration= $5\% \pm 1\%$, Test temperature= $+35 \pm 2$ °C, pH value= 6.5 to 7.2, Time= 48 hours, After removing the product, wash in warm water or salted water, then natural air-dried for 1 hour

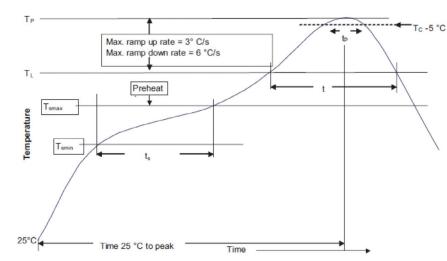
High temperature storage test: MIL-STD-202G Method 108, +125 °C, Duration= 1000 hours

Temperature cycling: JESD22 Method JA-104, High temperature = +125 °C, low temperature -40 °C, conversion time 30 minutes, 100 cycles.

Biased humidity: MIL-STD-202G Method 103, +85 °C, 85% RH, Duration= 1000 hours.

Life: MIL-STD-202 Method 108, 1000 hours, +85 °C at rated I_{ms} (Ambient plus self temperature rise no more than +125 °C)

Solder reflow profile



T_C -5 °C Table 1 - Standard SnPb solder (T_C)

| Package thickness | Volume mm3 <350 | Volume mm3 ≥350 |
|----------------------|-----------------------|-----------------------|
| <2.5 mm) | 235 °C | 220 °C |
| ≥2.5 mm | 220 °C | 220 °C |

Table 2 - Lead (Pb) free solder (T_C)

| Package thickness | Volume mm³ <350 | Volume mm³ 350 - 2000 | Volume mm³ >2000 |
|----------------------|-----------------------|-----------------------------|------------------------|
| <1.6 mm | 260 °C | 260 °C | 260 °C |
| 1.6 – 2.5 mm | 260 °C | 250 °C | 245 °C |
| >2.5 mm | 250 °C | 245 °C | 245 °C |

| Profile feature | Standard SnPb solder | Lead (Pb) free solder | |
|---|--------------------------|--------------------------|--|
| Preheat and soak • Temperature min. (T _{smin}) | 100 °C | 150 °C | |
| Temperature max. (T _{smax}) | 150 °C | 200 °C | |
| • Time (T _{Smin} to T _{Smax}) (t _S) | 60-120 seconds | 60-120 seconds | |
| Ramp up rate T _L to T _p | 3 °C/ second max. | 3 °C/ second max. | |
| Liquidous temperature (T_L) Time (t_L) maintained above T_L | 183 °C 60-150 seconds | 217 °C 60-150 seconds | |
| Peak package body temperature (Tp)* | Table 1 | Table 2 | |
| Time (t _p)* within 5 °C of the specified classification temperature (T _C) | 10 seconds* | 10 seconds* | |
| Ramp-down rate (T _p to T _L) | 6 °C/ second max. | 6 °C/ second max. | |
| Time 25 °C to peak temperature | 6 minutes max. | 8 minutes max. | |

 $^{^{\}star}$ Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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